

ULTRAVIOLET LASER MARKING MACHINE HBS-ZG-3



Technical Parameter	
Model	HBS-ZG-3 HBS-ZG-5
Laser Wavelength	355nm 266nm
Laser Power	3w /5w
Marking Area	50×50mm/100×100mm
Marking Speed	≤7000mm/s
Beam Quality	<2
Q Frequency Tuning	8Khz-15Khz
Min. Line Width	0.01mm
Min. Character Size	0.2mm
Repetition Accuracy	±0.003mm
Power Consumption	2kw
Power Supply	220V/ Single-Phase/50Hz/10A

Product Introduction

Ultraviolet Laser Marking Machine is self-developed by HBS and has the world's most advanced technology. It has following features: high electro-optical conversion rate, long working time of nonlinear crystal, high stability, high positioning accuracy,

high operation efficiency, optimized modular design for convenient installation and maintenance. Equipped with two-dimensional automated workstation, it can realize marking continuously in multi-stage or large-size marking. The laser marking line is very fine that suitable for marking with high demand, it's mainly applied to mark the products such as LCD screen, IC wafer and IC chips.

Applicable Materials & Industry

Mainly used in the marking and surface processing of materials such as of all sorts of glass, TFT, LCD screen, Plasma screen, textile products, ceramic chip, mono-crystal silicon wafer, IC chip, sapphire and thin polymer film. The main advantage of Ultraviolet laser is in the complementing of the shortcoming of other bandwidth lasers in precision machining and processing of special materials.

